

CLAIMS

1. A system, comprising:
a circuit portion, containing more than electrical conductors; and
a wirebonded assemblage, overlying the circuit portion,
5 wherein the wirebonded assemblage comprises a plurality of wirebonded wires,
wherein each of the plurality of wirebonded wires are electrically coupled, and
wherein the wirebonded assemblage provides electrical shielding for the circuit
portion.
2. A system as in claim 1, wherein the circuit portion comprises at least one of an active
10 component and a passive component.
3. A system as in claim 1, wherein the circuit portion comprises at least a portion of an
integrated circuit.
4. A system as in claim 1, wherein the plurality of wirebonded wires comprise at least
five wirebonded wires.
- 15 5. A system as in claim 1, wherein the circuit portion has a non-linear geometry.
6. A system as in claim 1, wherein the circuit portion is located in a cavity of a substrate.
7. A system as in claim 1, wherein the wirebonded assemblage provides heat spreading
for the circuit portion.
8. A system as in claim 1, wherein at least one of the plurality of wirebonded wires is
20 coupled to a predetermined voltage level.
9. A system as in claim 8, wherein the predetermined voltage level is approximately
ground.
10. A system as in claim 1, further comprising:
a second circuit portion, overlying the wirebonded assemblage.

11. A system as in claim 10, wherein the second circuit portion is electrically coupled to the wirebonded assemblage.
12. A system as in claim 1, wherein at least one of the plurality of wirebonded wires is not wirebonded to the circuit portion.
- 5 13. A system as in claim 1, further comprising:
a second plurality of wirebonded wires electrically coupled to the circuit portion for communicating electrical signals.
14. A system as in claim 1, wherein a first one of the plurality of wirebonded wires is neither parallel nor perpendicular to a second one of the plurality of wirebonded wires.
- 10 15. A system as in claim 1, further comprising:
a conductive layer underlying the circuit portion, wherein the conductive layer is electrically coupled to the wirebonded assemblage to encapsulate the circuit portion.
- 15 16. A method for forming a wirebonded assemblage, comprising:
providing a circuit portion having at least one of an active component and a passive component;
wirebonding a plurality of wirebonded wires overlying the least one of the active component and the passive component;
electrically coupling the plurality of wirebonded wires; and
20 electrically shielding the least one of the active component and the passive component using the plurality of wirebonded wires.
17. A method as in claims 16, wherein an attachment point for a first end of each of the plurality of wirebonded wires is overlying an active area of the circuit portion.
- 25 18. A system as in claim 16, wherein the circuit portion comprises an integrated circuit and wherein at least one of the plurality of wirebonded wires overlies at least two edges of the circuit portion.

19. A system, comprising:

a circuit portion, containing more than electrical conductors;

a first wirebonded wire, overlying any two edges of the circuit portion; and

a second wirebonded wire, overlying any two edges of the circuit portion;

5 wherein the first wirebonded wire and the second wirebonded wire are electrically coupled, and

wherein the first wirebonded wire and the second wirebonded wire are used to provide electrical shielding for the circuit portion.

20. A system as in claim 19, wherein the circuit portion comprises an integrated circuit.

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